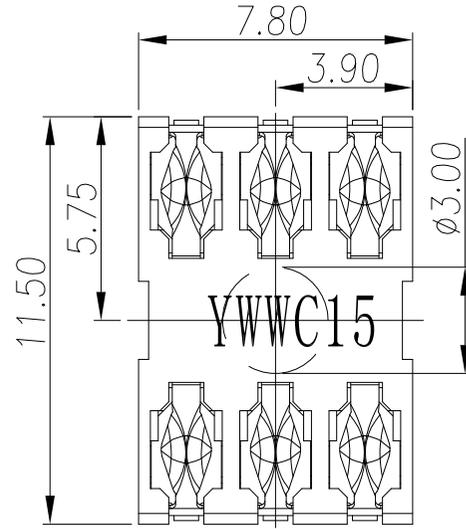
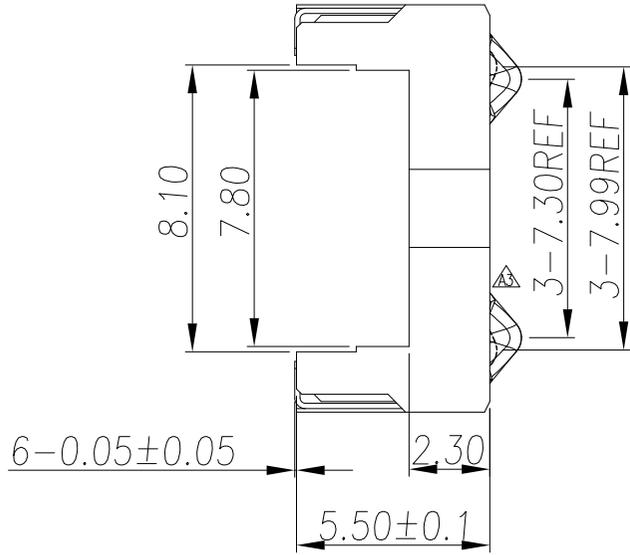


GP Component

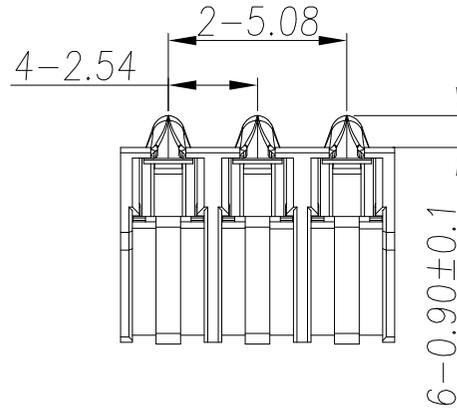
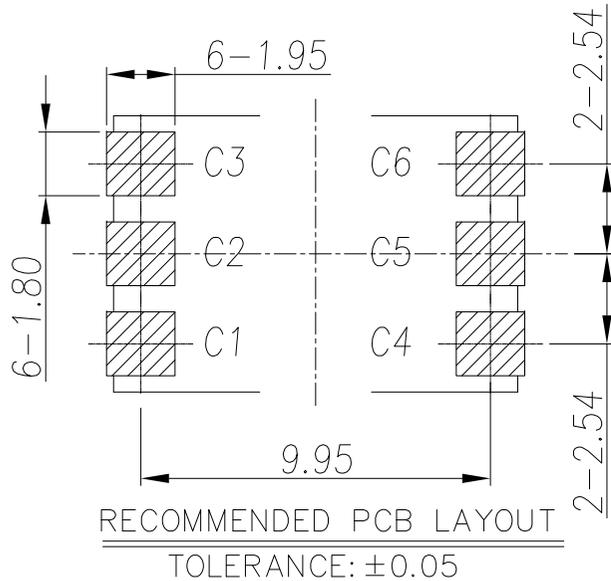
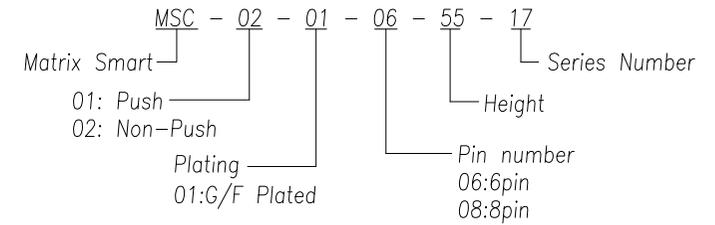
| REV. | ECN NO. | LOCATIONS | DESCRIPTION | DATE | DESIGN |
|------|---------|-----------|-----------------|------------|--------|
| A0 | | | Initial | 2022/08/18 | Hanson |
| A1 | | | Change Humidity | 2022/12/30 | Hanson |
| A2 | | | Add Chamfer | 2023/01/12 | Hanson |
| A3 | | | 接觸點改為點接觸 | 2023/10/27 | Hanson |



Notes:

- Material:
 - Housing: High Temperature Thermoplastic
 - Terminal: Copper Alloy
- Plating:
 - Terminal: 50u" Ni Underplated Overall
 - G/F Plated On Contact Area
 - G/F Plated On Solder Area
- Technical Speciality:
 - Rated Voltage: 30V
 - Current Rating: 0.5A
 - Insulation Resistance: 1000MΩ Min.
 - Contact Resistance: 100mΩ Max.
 - Withstanding Voltage: 500V DC For 1 Minutes.
 - Durability: 10000 cycles min
 - Operating Temperature: -40°C ~ +85°C Humidity 90% R.H Max.

MATRIX PART NO:



| Matrix Electronics Co.,Ltd | | | | |
|--|--------------------------------|----------------------|------------------------------------|--------------------|
| TOLERANCE: X:X ±0.30 X:XX ±0.20 X:XXX ±0.10 ANGLE: ±5° | DESIGN BY : Hanson Huang | DATE : 2023/10/27 | PART NAME: Smart Card Connector | |
| UNIT: mm [inch] SCALE: 1:1 SIZE: A4 | CHECKED BY: Vicky Hsieh | DATE : 2023/10/27 | PART NO. | MSC-02-01-06-55-17 |
| | APPROVED BY1: Richard Hsieh | DATE : 2023/10/27 | MOLD NO. | NA |
| | APPROVED BY2: Richard Hsieh | DATE : 2023/10/27 | DRAW NO. | |
| | | | SHEET NO. | 1 OF 1 |